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# Product Change Notification - JAON-20TVFV764

12 Aug 2016
SMSC
CCB 1787 Final Notice: Qualification of ASE site for LAN9311 and LAN9313 device families in 128L
TQFP package using CuPdAu wire, C7025 lead frame, CRM1076 die attach and G631H molding
compound material
PCN Status: Final notification

## **Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

## **Description of Change:**

Qualification of ASE assembly site for LAN9311 and LAN9313 device families available in 128L TQFP package using palladium coated copper with gold flash (CuPdAu) bond wire, C7025 lead frame, CRM-1076 die attach and G631H molding compound material.

#### Pre Change:

Assembled at ATT assembly site using Gold (Au) bond wire, C194 lead frame, 3230 die attach and G700L molding compound material

## Post Change:

Assembled at ASE assembly site using palladium coated copper with gold flash (CuPdAu) bond wire, C7025 lead frame, CRM-1076 die attach and G631H molding compound material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	ATT assembly site	ASE assembly site
Wire material	Au wire	CuPdAu wire
Die attach material	3230	CRM1076
Molding compound material	G700L	G631H
Lead frame material	C194	C7025

Impacts to Data Sheet: None

Change Impact: None

Reason for Change: To improve Improve On-Time Delivery Performance by qualifying ASE assembly site. Change Implementation Status: In Progress

### **Estimated First Ship Date:**

September 16, 2016 (date code: 1637)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

### Time Table Summary:

	November 2015			->	August 2016			September 2016						
WW	45	46	47	48		31	32	33	34	35	36	37	38	39
Initial PCN Issue Date				Х										
Qual Report Availability							х							
Final PCN Issue Date							Х							
Estimated Implementation Date												Х		

Method to Identify Change: Traceability code

**Qualification Report:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report.

Revision History: November 27, 2015: Issued initial notification. August 12, 2016: Issued final notification. Attached the qualification report. Revised the estimated first ship date from March 16, 2016 to September 16, 2016.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

#### Attachment(s):

PCN\_JAON-20TVFV764\_Qual\_Report.pdf PCN\_JAON-20TVFV764\_Affected\_CPN.pdf PCN\_JAON-20TVFV764\_Affected\_CPN.xls

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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JAON-20TVFV764 - CCB 1787 Final Notice: Qualification of ASE site for LAN9311 and LAN9313 device families in 128L TQFP package using CuPdAu wire, C7025 lead frame, CRM1076 die attach and G631H molding compound.

Affected Catalog Part Numbers (CPN)

PCN_JAON-20TVFV764					
CATALOG_PART_NBR					
LAN9311-NU					
LAN9313-NU					
LAN9313-NU-TR					